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Li

(10)

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(54) COMBINED WIRELESS EARPHONE AND CASE

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(**) Term: 15 Years

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(30) Foreign Application Priority Data

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(52) U.S. Cl.

USPC D14/223; D13/108

(58) Field of Classification Search

USPC D14/223; D3/201, 273, 274, 294; D13/108; D24/174; 128/864-866;

(Continued)

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Primary Examiner — Paula Allen Greene

(74) Attorney, Agent, or Firm — Jeenam Park

(57) CLAIM

The ornamental design for a combined wireless earphone and case, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a combined wireless earphone and case showing my new design;

FIG. 2 is a perspective view thereof;

FIG. 3 is a front, right, and top perspective view of the case for a combined wireless earphone and case thereof, shown separately for ease of illustration, in a closed position;

FIG. 4 is a rear, left and bottom perspective view thereof;

FIG. 5 is a front view thereof;

FIG. 6 is a rear view thereof;

FIG. 7 is a left side view thereof;

FIG. 8 is a right side view thereof;

FIG. 9 is a top plan view thereof;

FIG. 10 is a bottom plan view thereof;

FIG. 11 is a front, right, and top perspective view of the wireless earphones of the combined wireless earphones and case thereof, shown separately for ease of illustration;

FIG. 12 is a rear, left and bottom perspective view thereof;

FIG. 13 is a front view thereof;

FIG. 14 is a rear view thereof;

FIG. 15 is a left side view thereof;

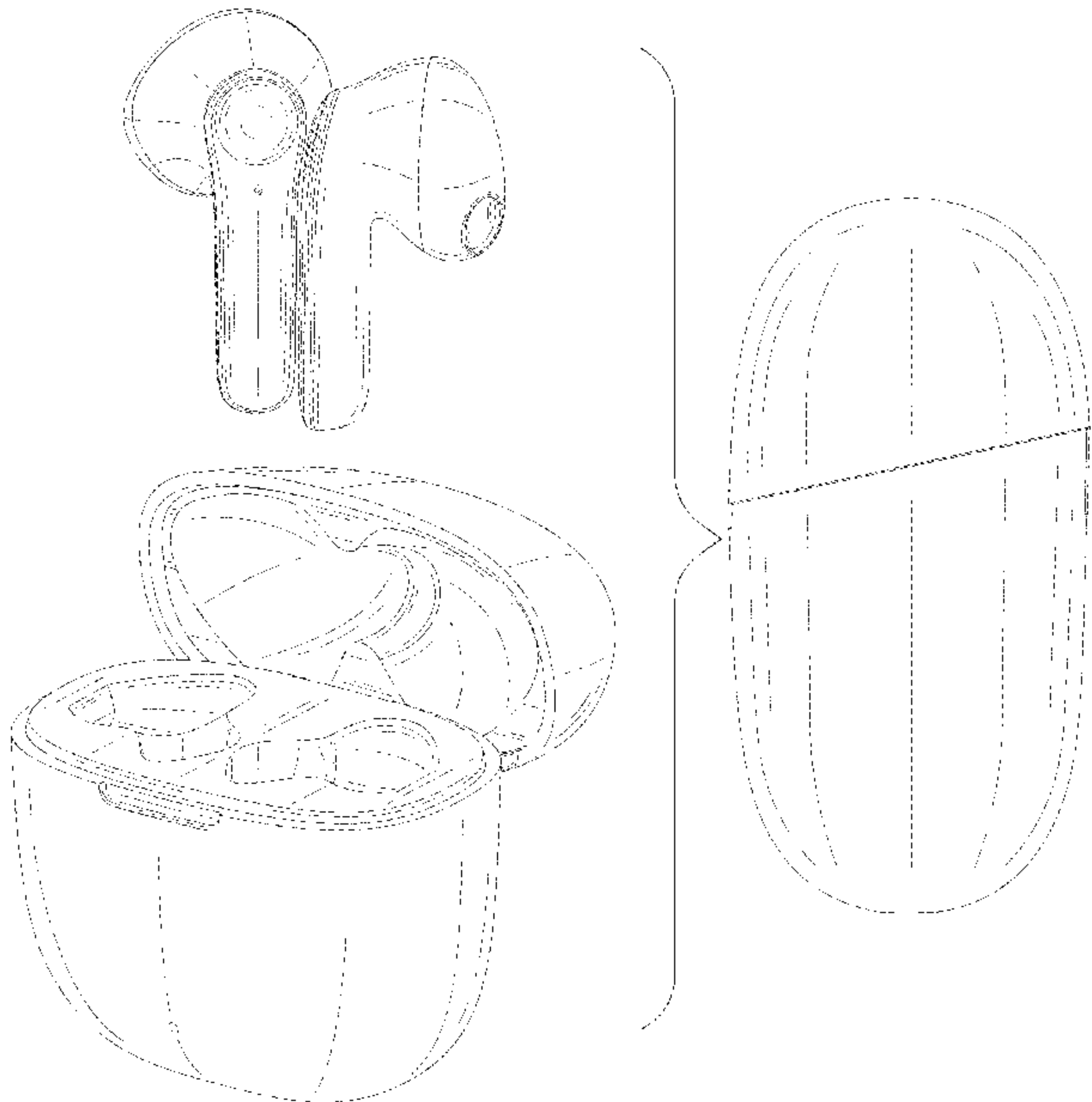
FIG. 16 is a right side view thereof;

FIG. 17 is a top plan view thereof; and,

FIG. 18 is a bottom plan view thereof.

The broken lines shown in the drawings illustrate portions of the combined wireless earphone and case that form no part of the claimed design.

1 Claim, 18 Drawing Sheets



(58) **Field of Classification Search**
USPC 381/380–381, 322, 328; D9/420, 521,
D9/529
CPC H04R 1/10; H04R 25/00; H04R 25/02;
H04R 1/1066; H04R 1/1016; H04R
5/033; H04R 5/0335; H04R 1/1091; H02J
7/0044; A45C 11/24; A45C 11/16; B65D
43/16
See application file for complete search history.

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FIG. 1

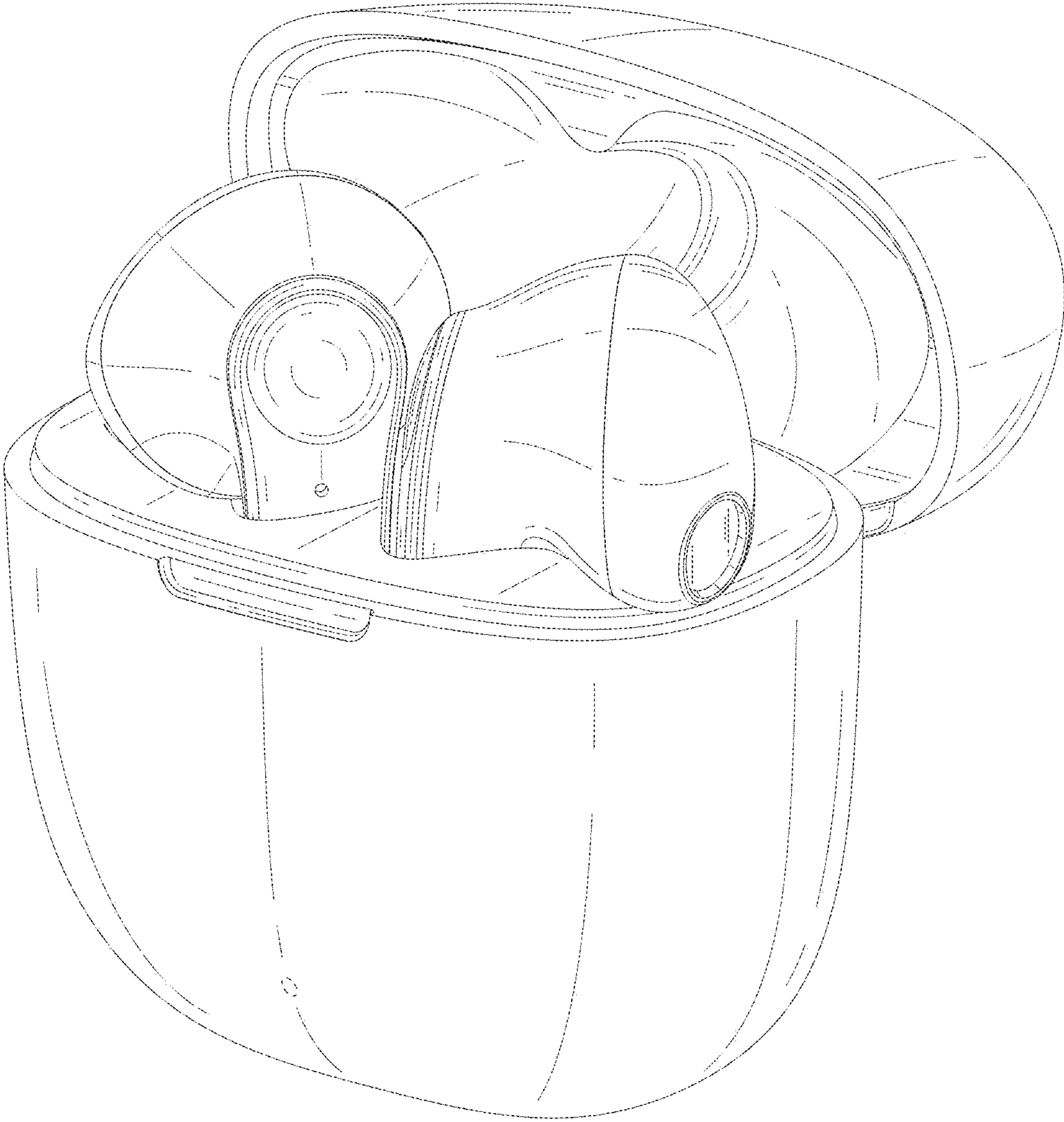


FIG. 2

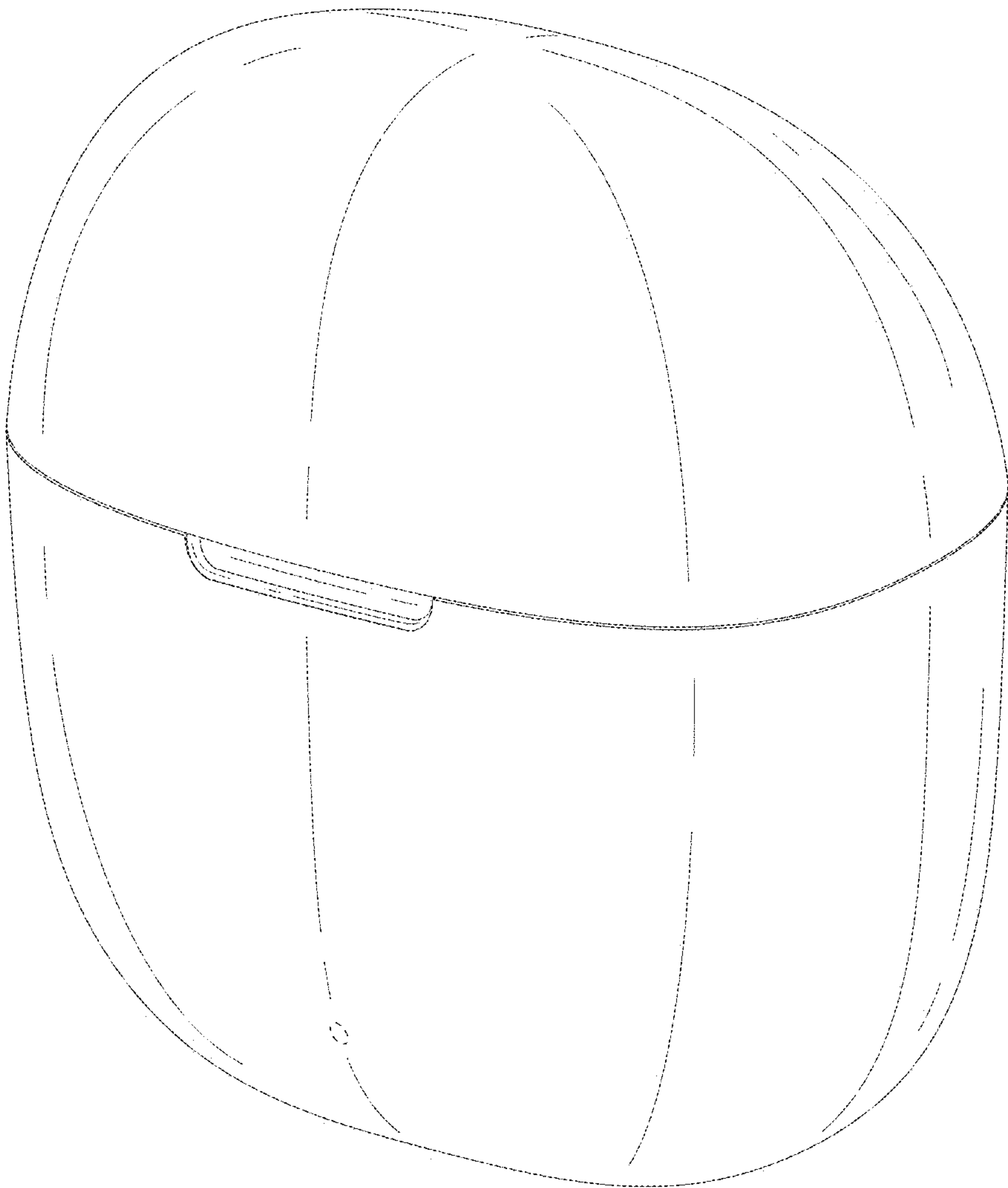


FIG. 3

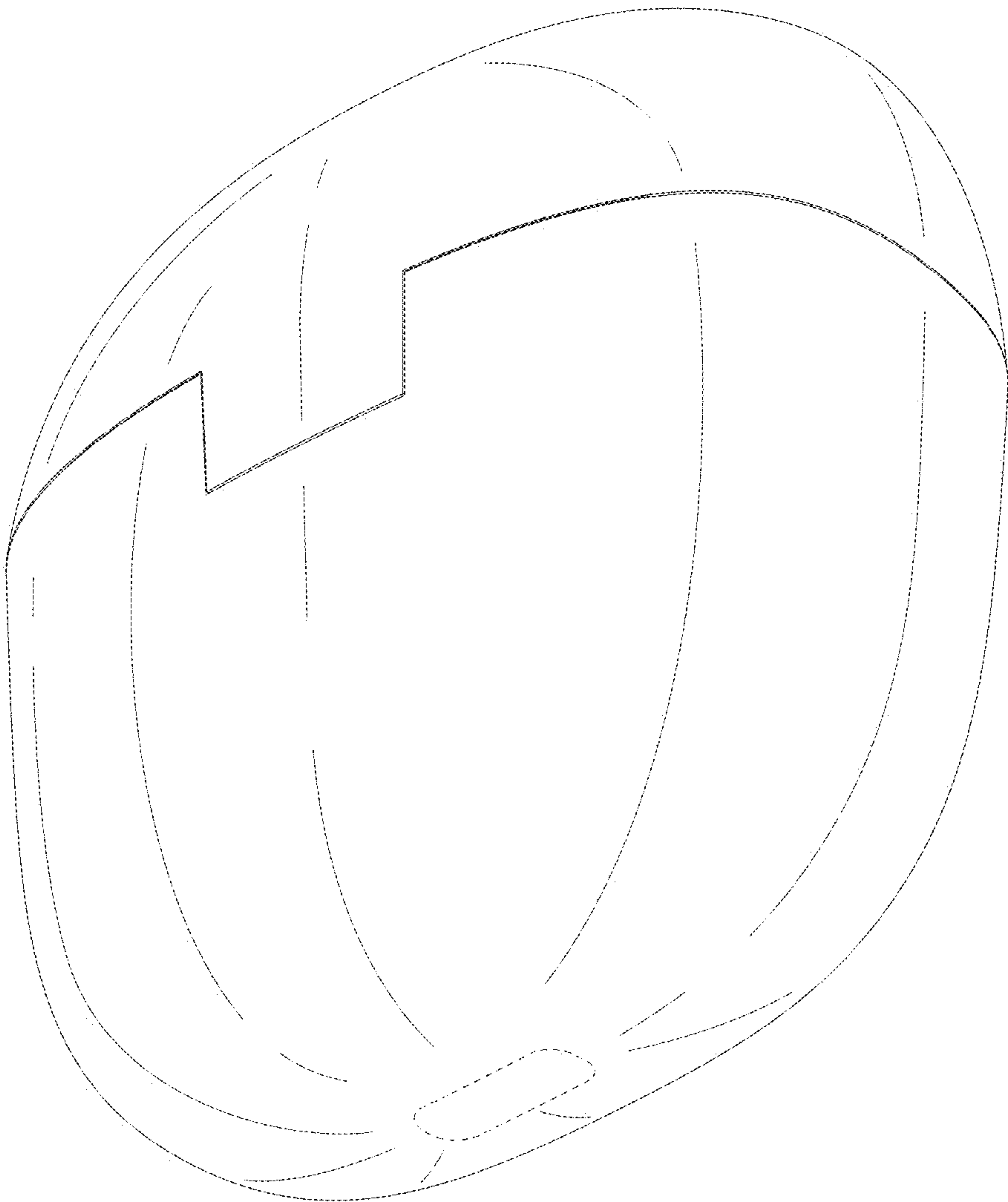


FIG. 4

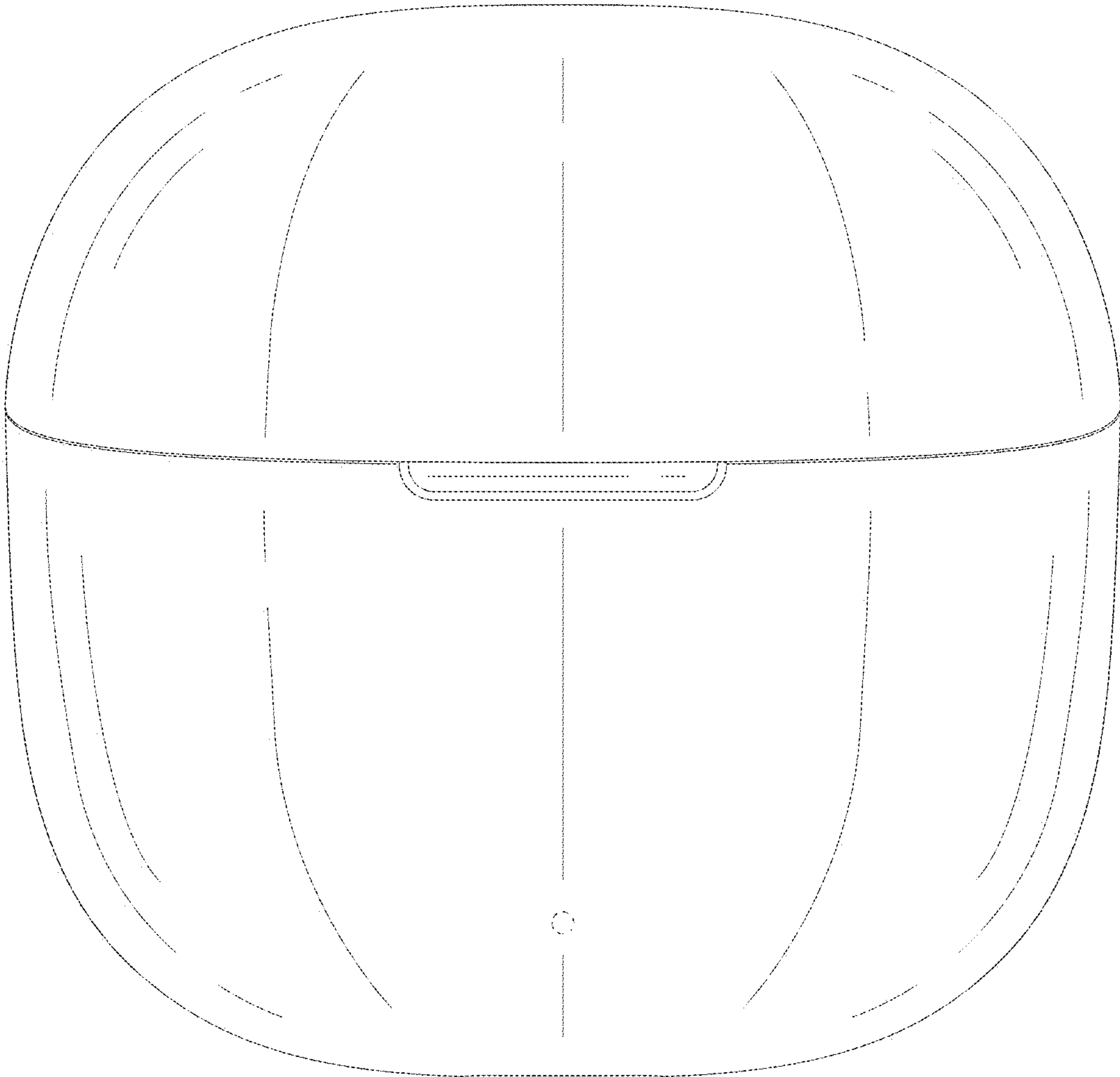


FIG. 5

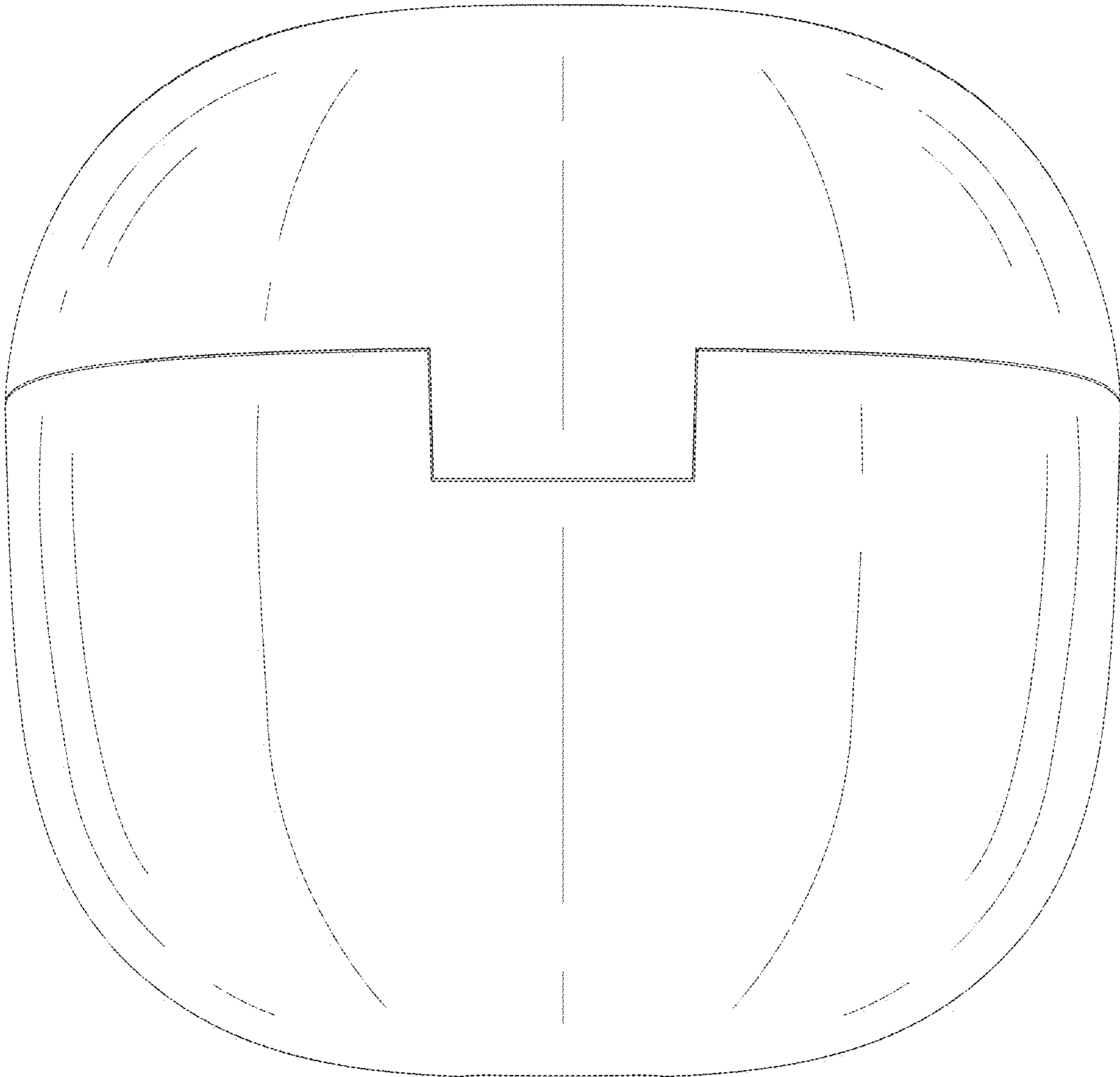


FIG. 6

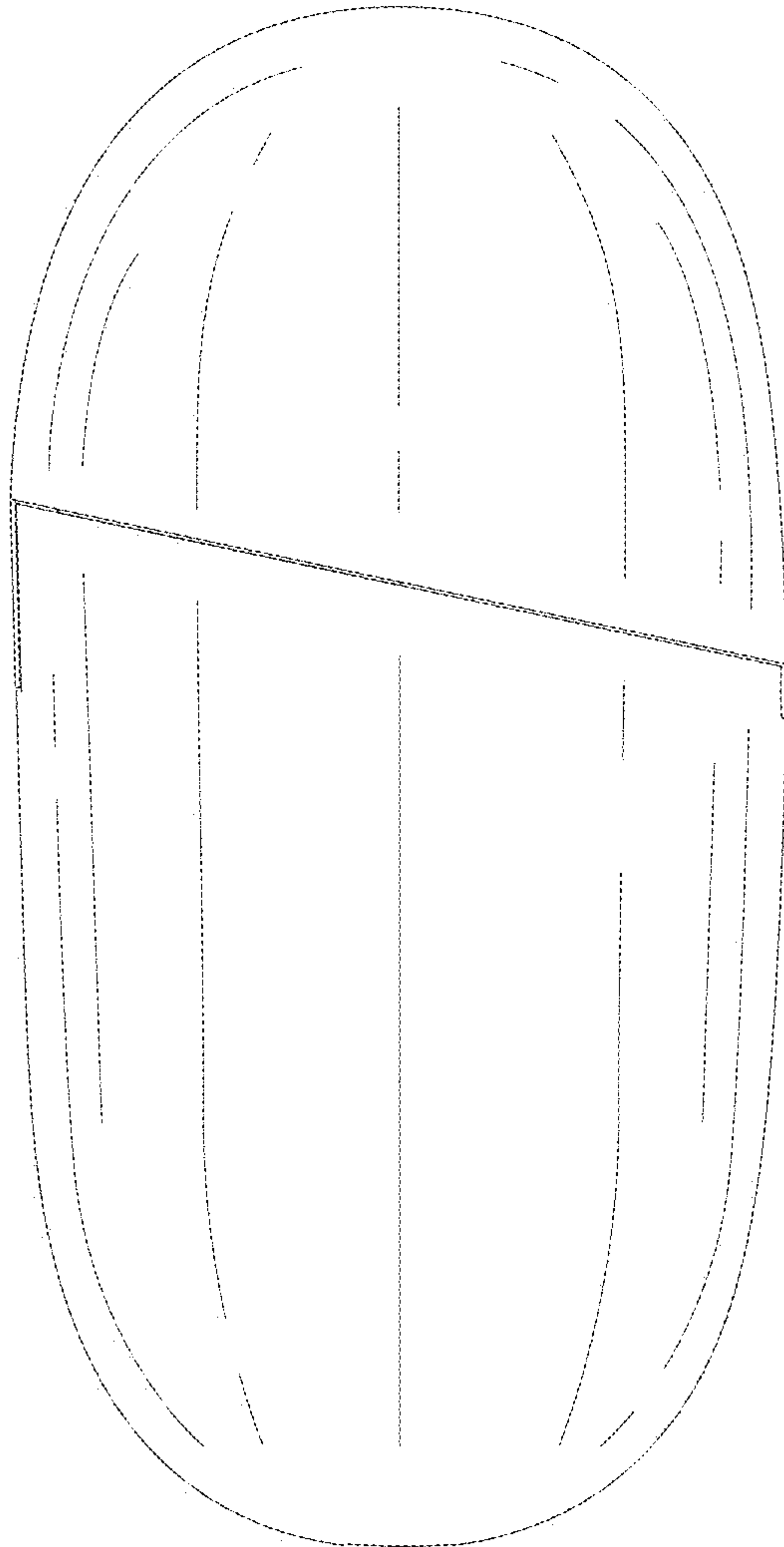


FIG. 7

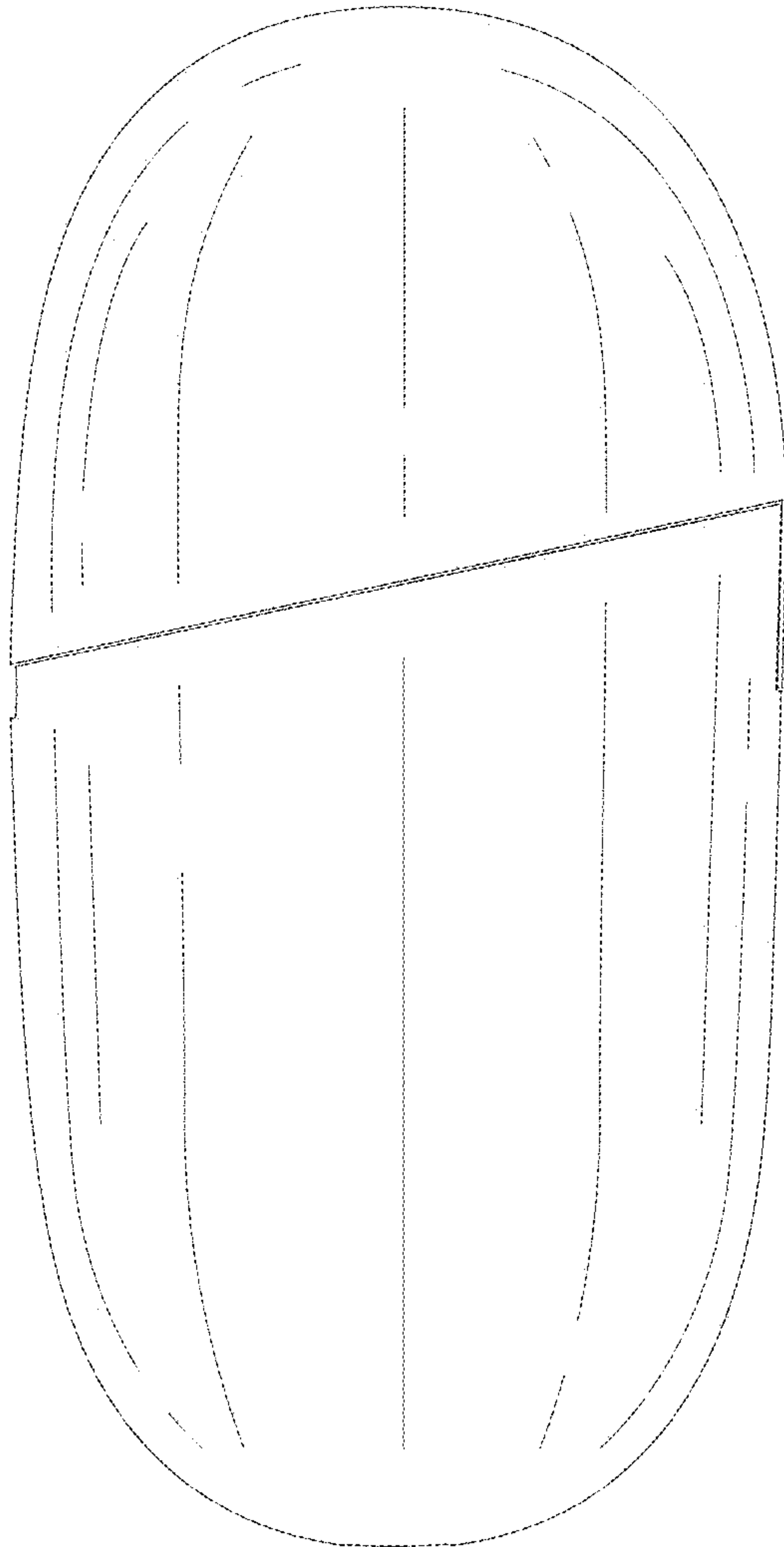


FIG. 8

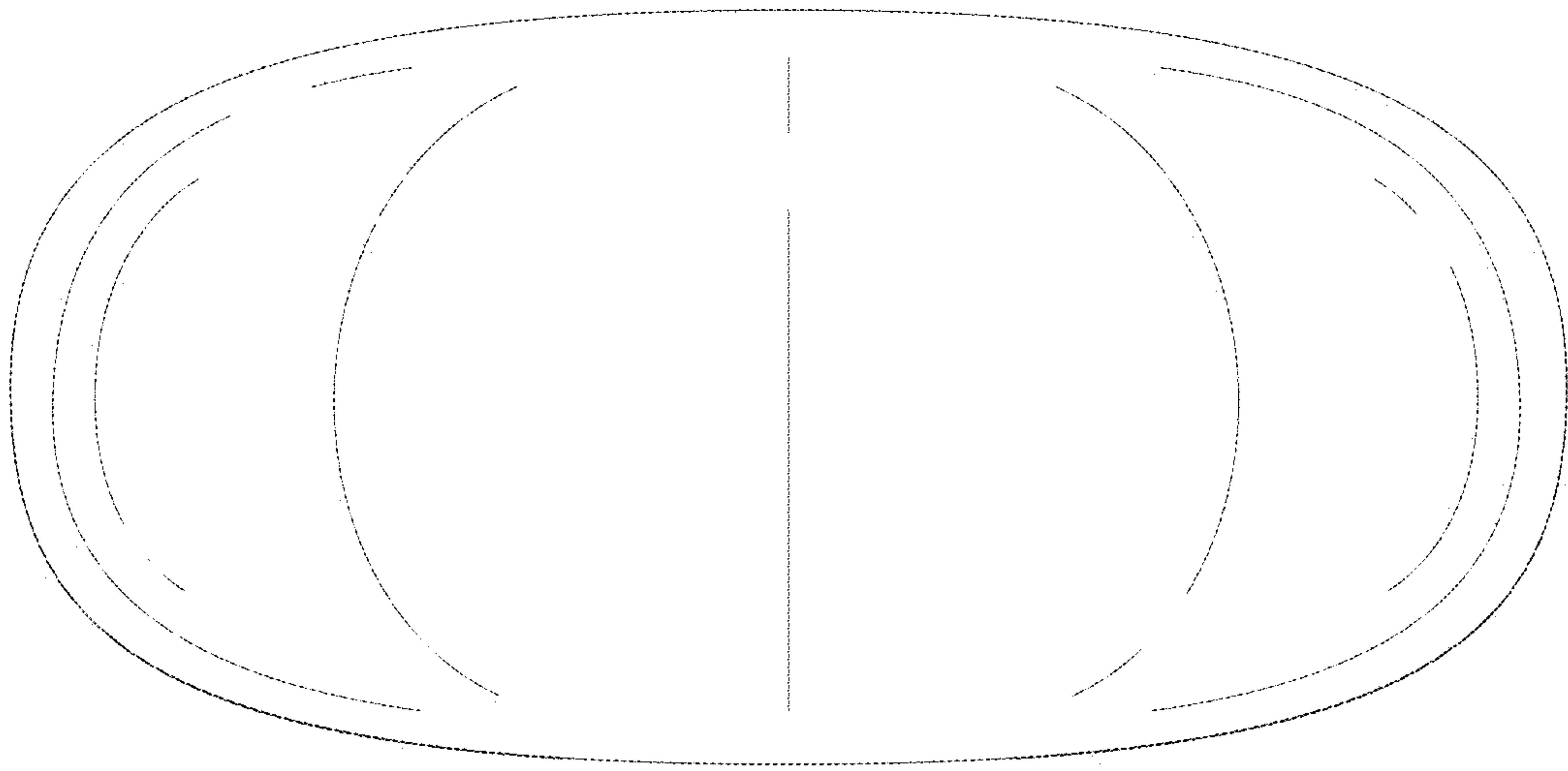


FIG. 9

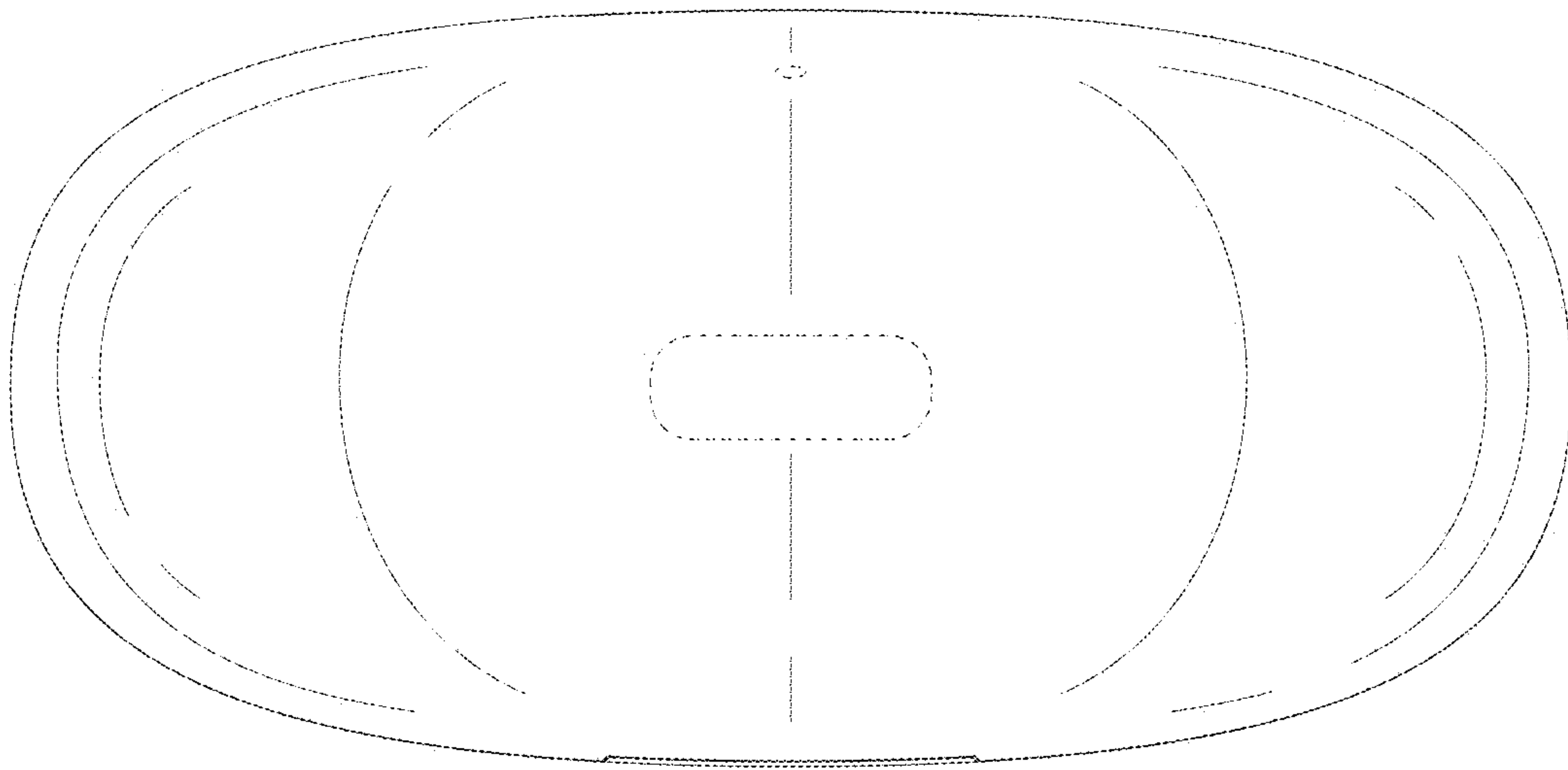


FIG. 10

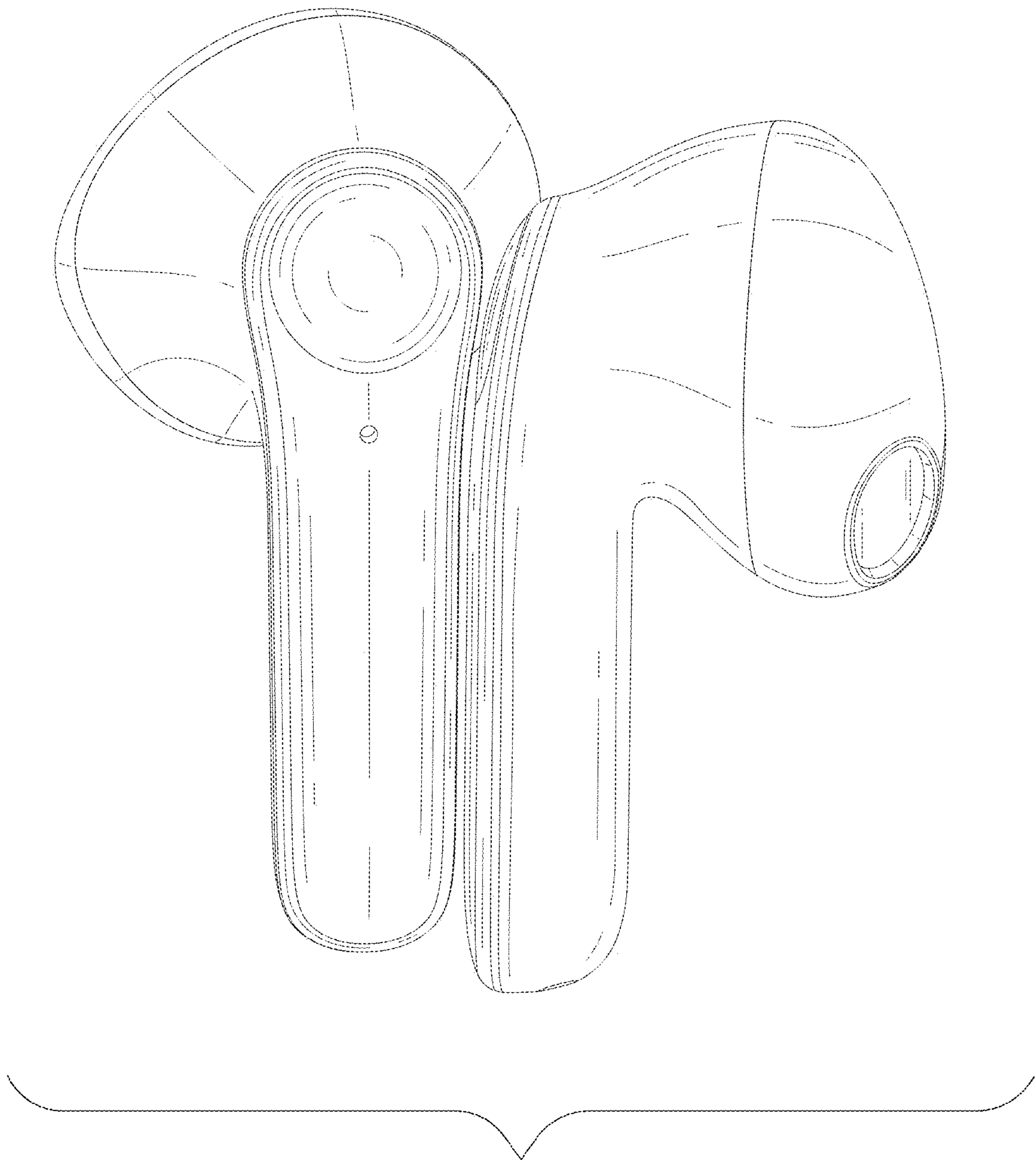


FIG. 11

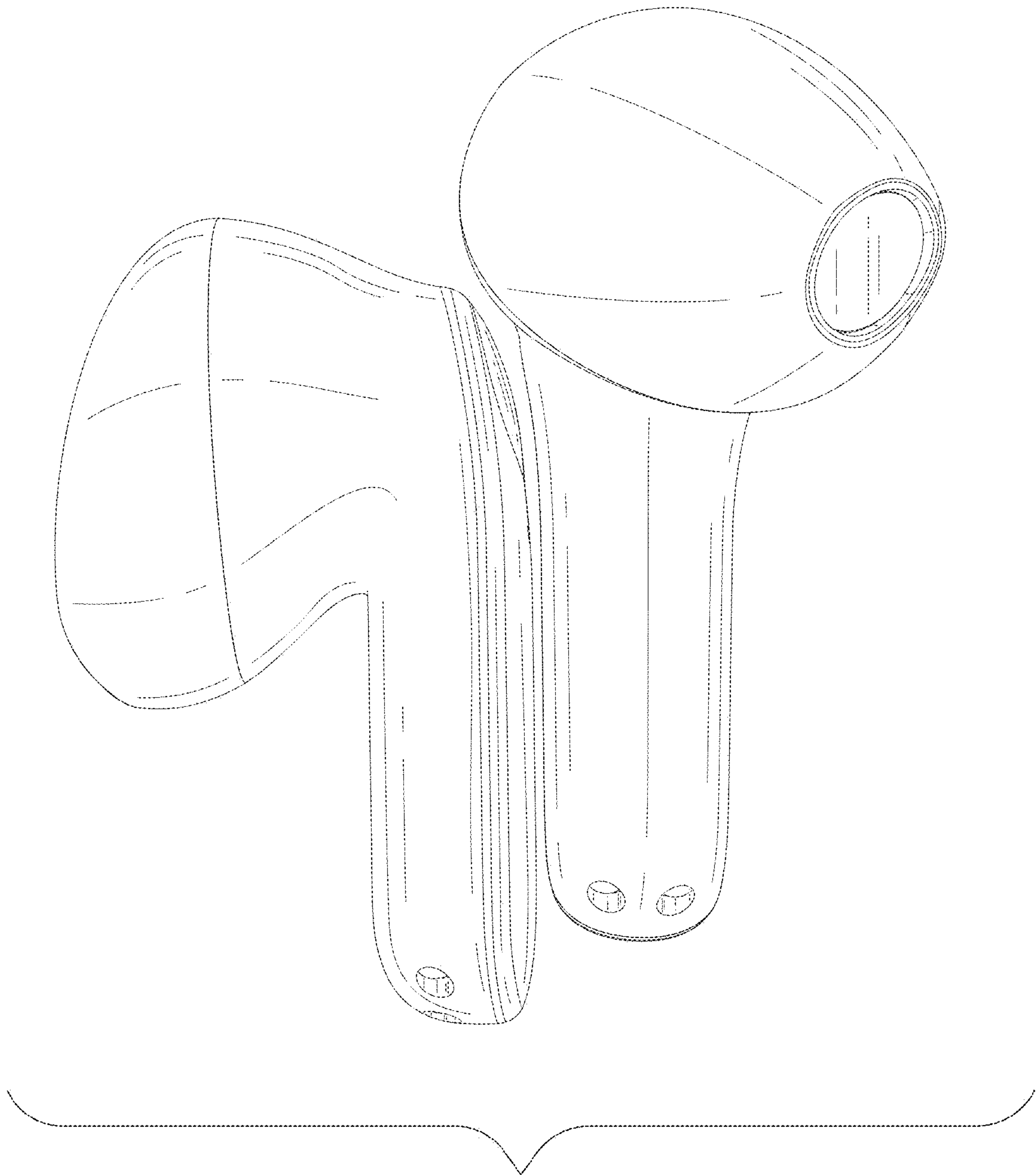


FIG. 12

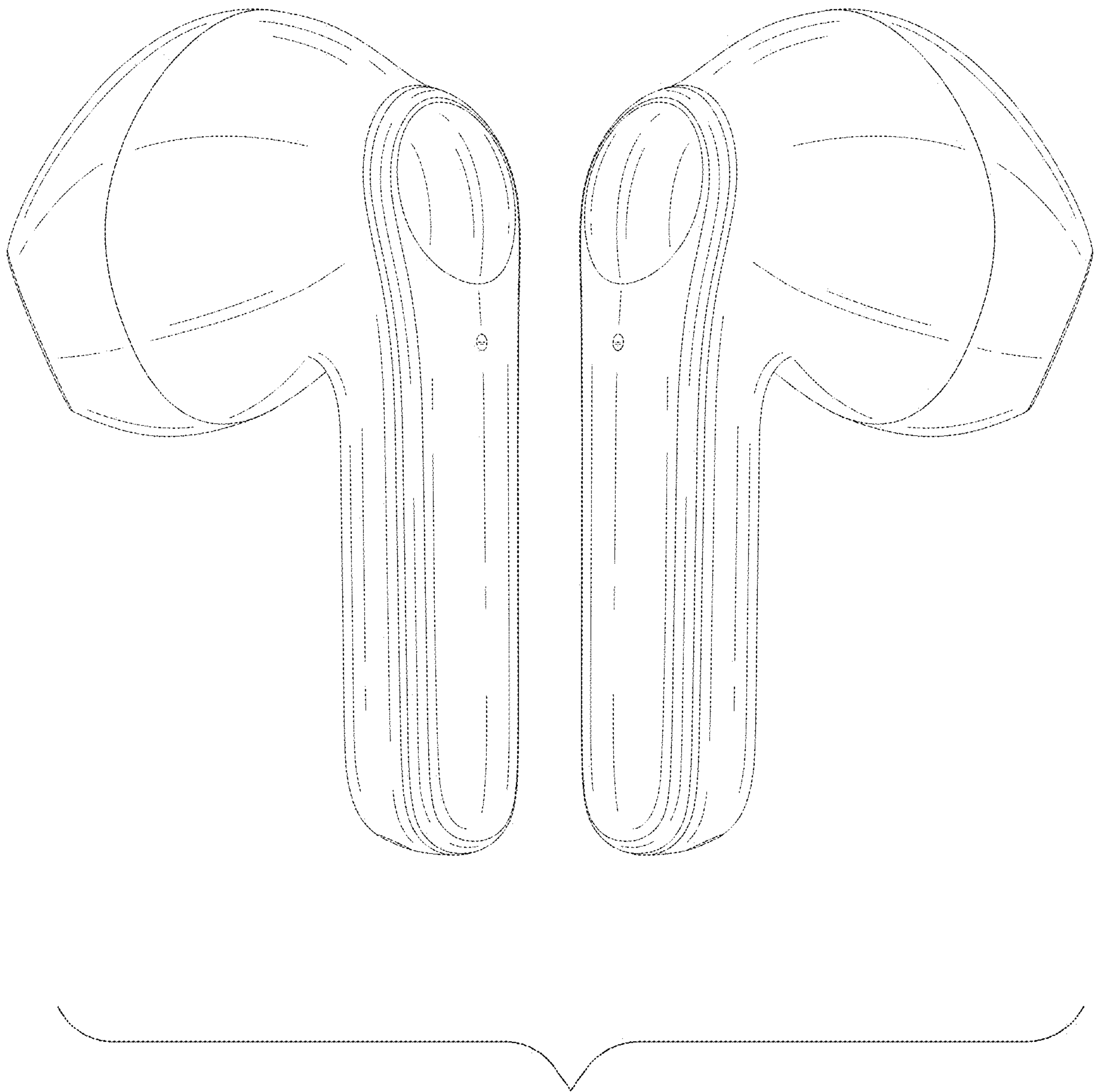


FIG. 13

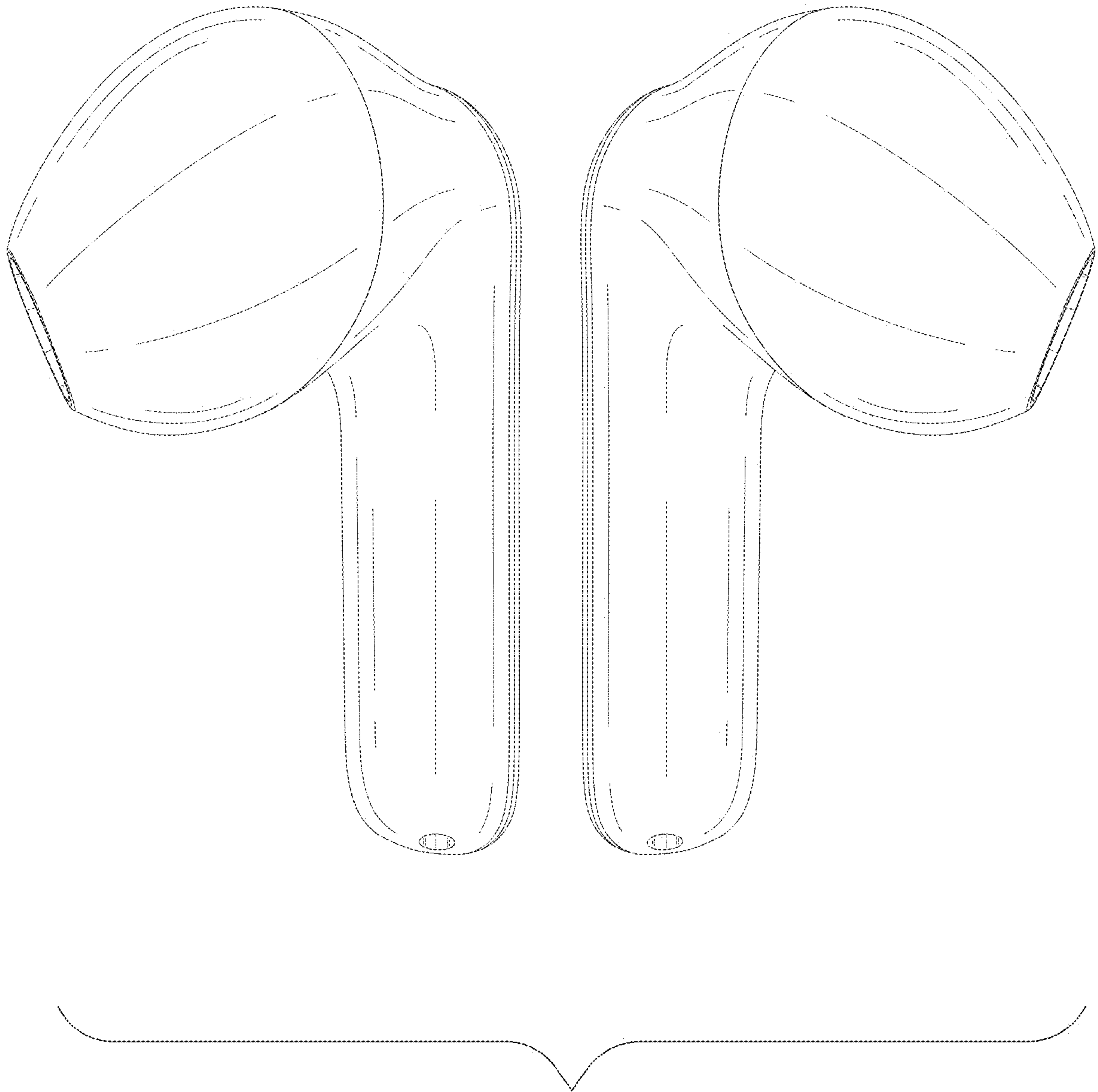


FIG. 14

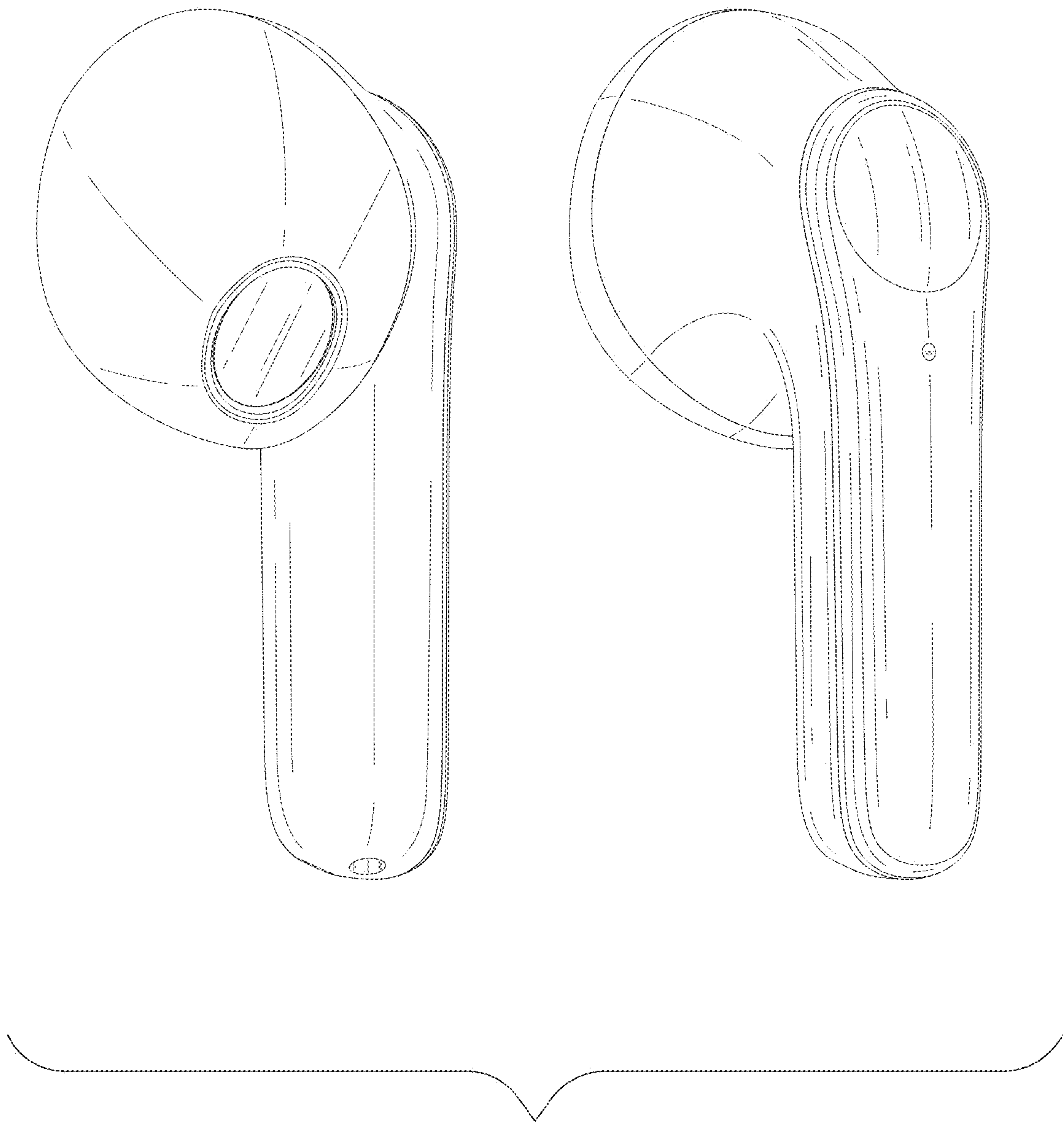


FIG. 15

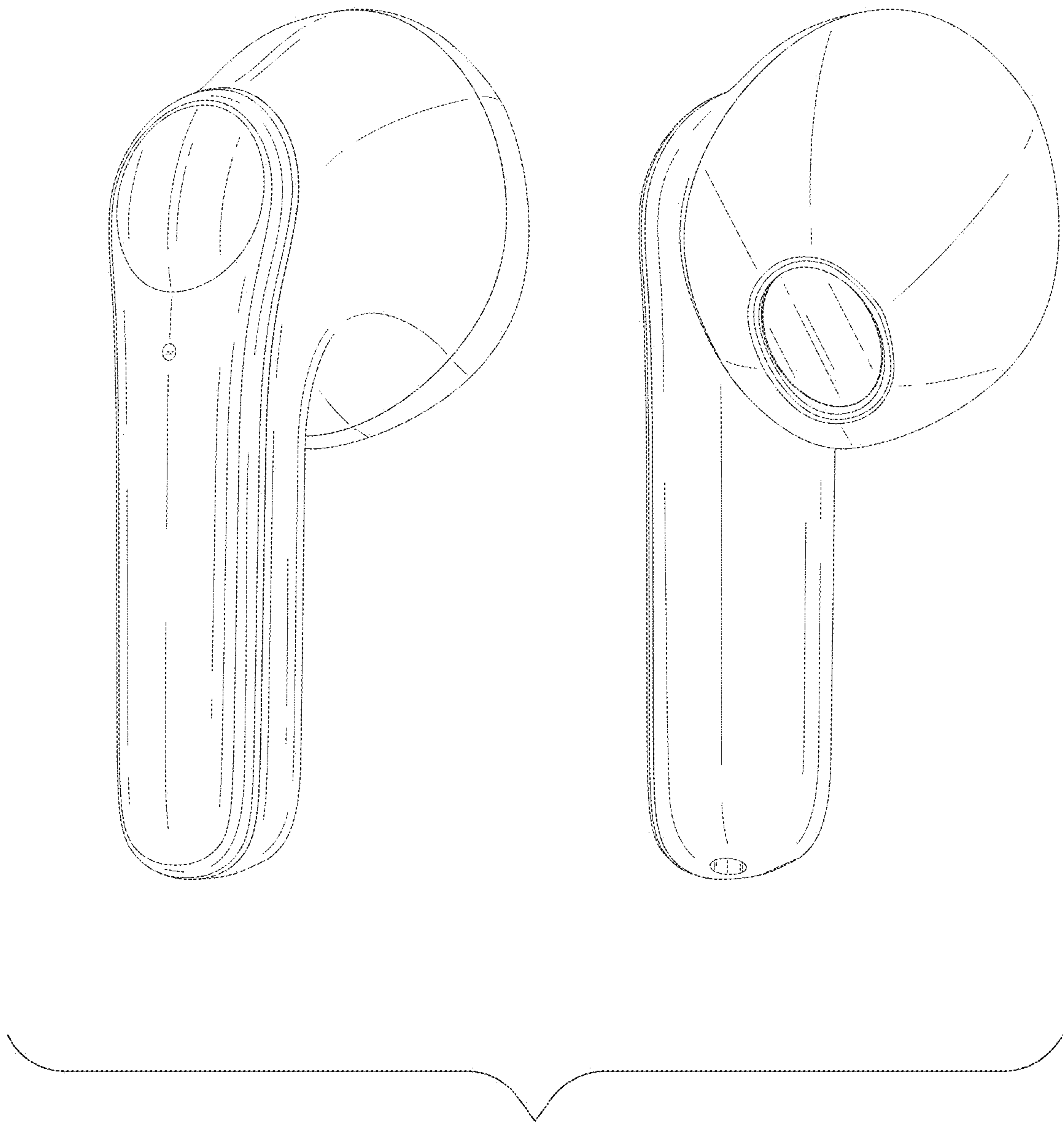


FIG. 16

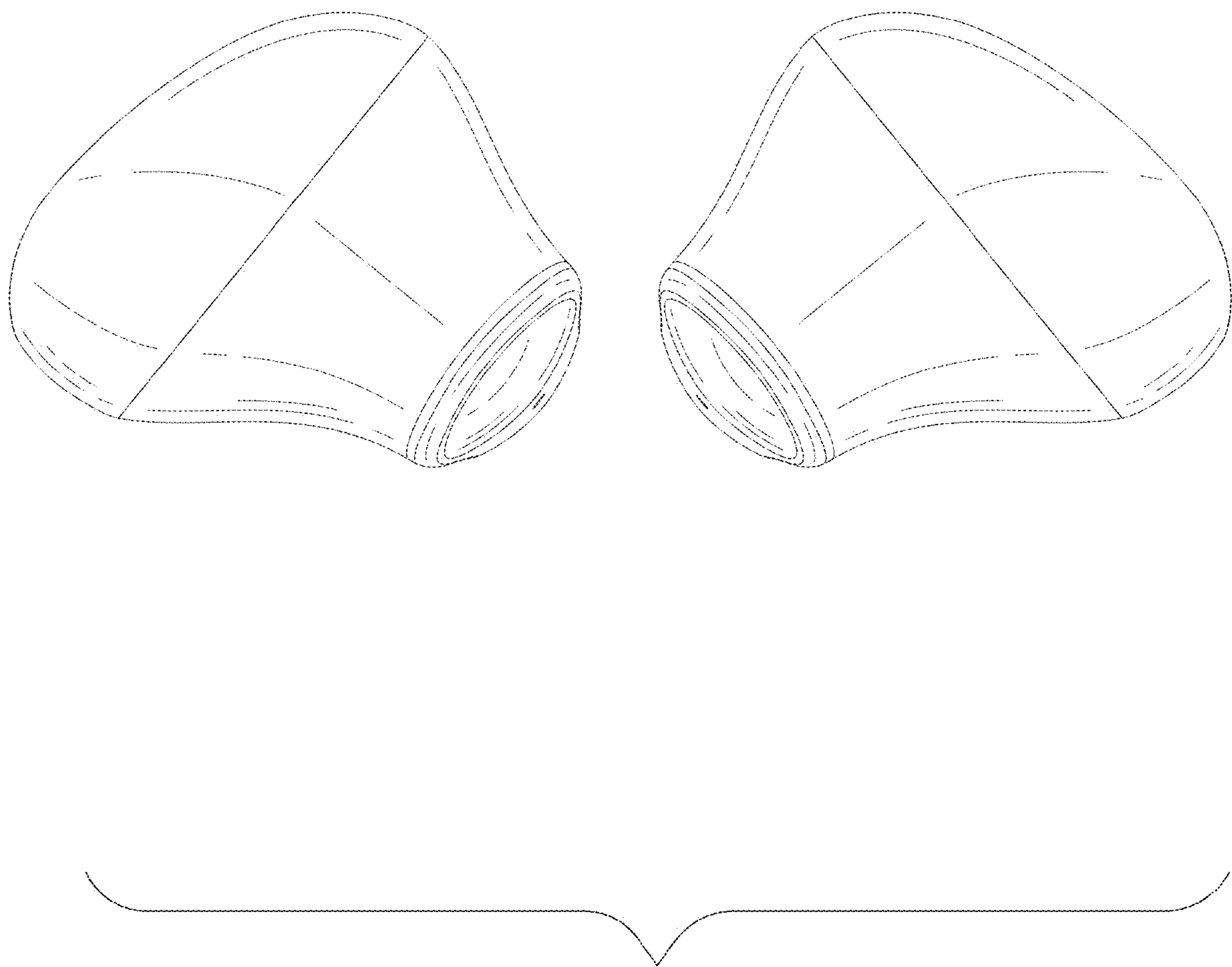


FIG. 17

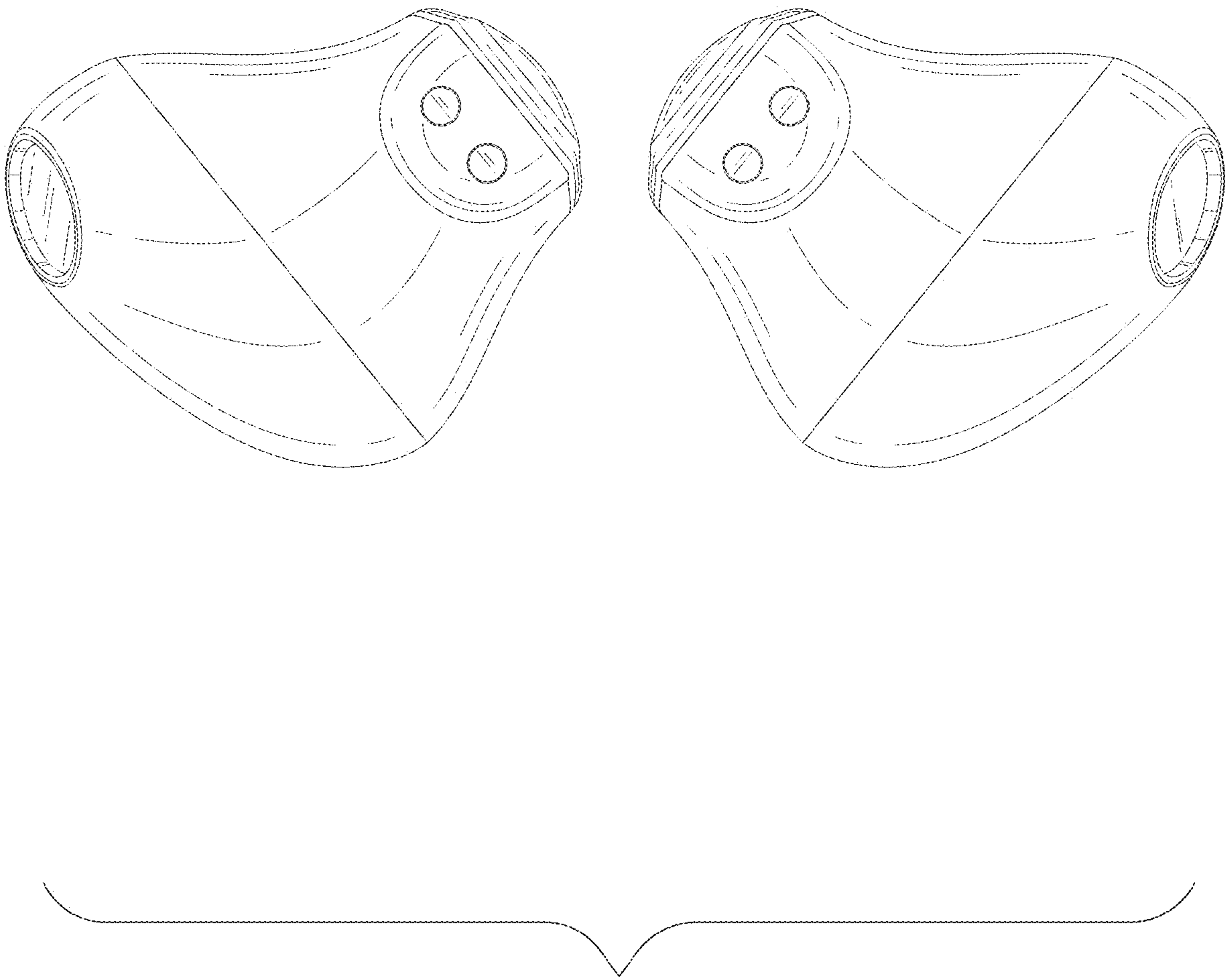


FIG. 18